


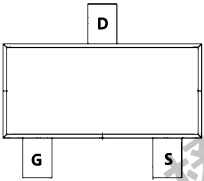
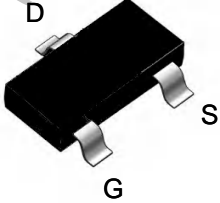
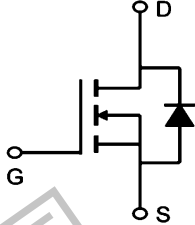


TMG04N10I

N-Channel Enhancement Mosfet

<p>General Description</p> <ul style="list-style-type: none"> • Low $R_{DS(ON)}$ • RoHS and Halogen-Free Compliant <p>Applications</p> <ul style="list-style-type: none"> • Load switch • PWM 	<p>General Features</p> <p>$V_{DS} = 100V$ $I_D = 4A$ $R_{DS(ON)} = 110\text{ m}\Omega$ (typ.) @ $V_{GS} = 10V$</p> <p>100% UIS Tested 100% R_g Tested</p> 
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I:SOT-23

Marking: 4T10

Absolute Maximum Ratings ($T_C = 25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D @ T_A = 25^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	4	A
$I_D @ T_A = 70^\circ\text{C}$	Continuous Drain Current, $V_{GS} @ 10V^1$	2.8	A
I_{DM}	Pulsed Drain Current ²	15	A
$P_D @ T_A = 25^\circ\text{C}$	Total Power Dissipation	3.5	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ\text{C}$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient	---	162	$^\circ\text{C/W}$
$R_{\theta JC}$	Thermal Resistance Junction Case	---	---	$^\circ\text{C/W}$

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Electrical Characteristics: ($T_J=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\ \mu\text{A}$	100	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=100V$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=250\ \mu\text{A}$	1	2	3	V
$R_{DS(on)}$	Drain-Source On Resistance <small>note2</small>	$V_{GS}=10V, I_D=5A$	---	110	140	m Ω
		$V_{GS}=4.5V, I_D=3A$	---	---	---	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=50V, V_{GS}=0V,$ $f=1\text{MHz}$	---	202	---	pF
C_{oss}	Output Capacitance		---	28.1	---	
C_{rss}	Reverse Transfer Capacitance		---	1.3	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	$V_{GS}=10V, V_{DS}=50V,$ $R_G=2\Omega, I_D=4A$	---	14.7	---	ns
t_r	Rise Time		---	3.5	---	ns
$t_{d(off)}$	Turn-Off Delay Time		---	20.9	---	ns
t_f	Fall Time		---	2.7	---	ns
Q_g	Total Gate Charge	$V_{GS}=10V, V_{DS}=50V,$ $I_D=4A$	---	4.3	---	nC
Q_{gs}	Gate-Source Charge		---	1.5	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	1.1	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage	$V_{GS}=0V, I_S=4\text{A}$	---	---	1.3	V
t_{rr}	Body Diode Reverse Recovery Time	$I_S=4A, V_R=50V$	---	32.1	---	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$di/dt=100A/\mu\text{s}$	---	39.4	---	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature
2. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$

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Typical Characteristics

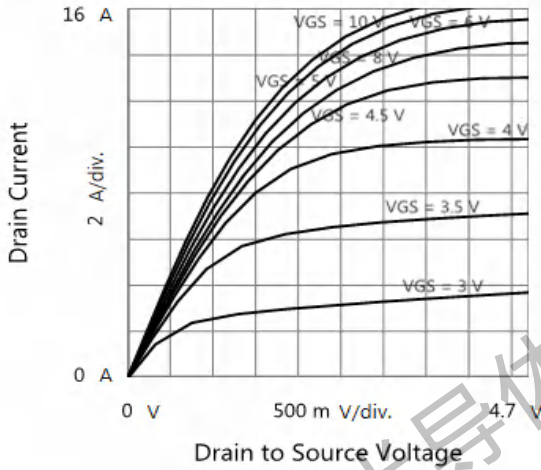


Figure1: Output Characteristics

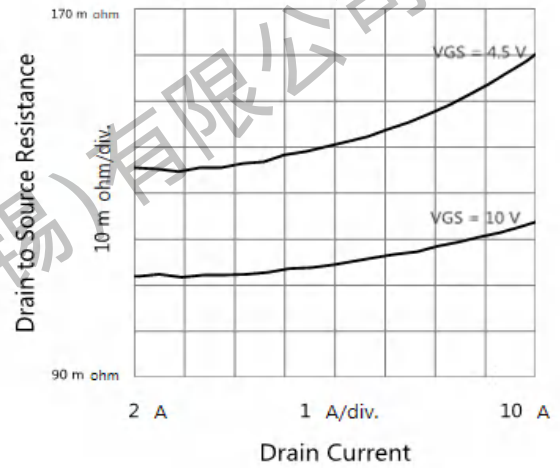


Figure 2: Drain to Resistance vs. Drain Current

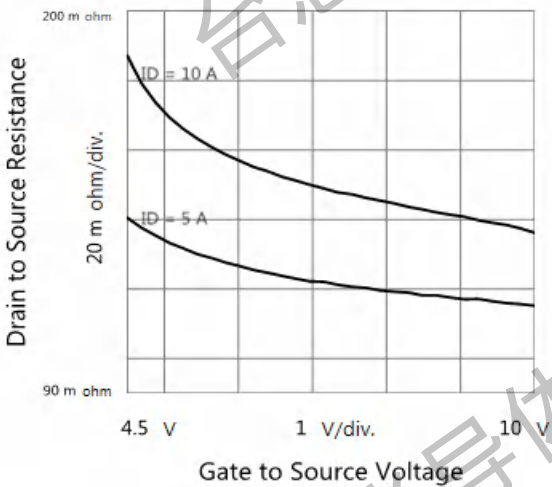


Figure 3: Drain to Resistance vs. Gate to Source Voltage

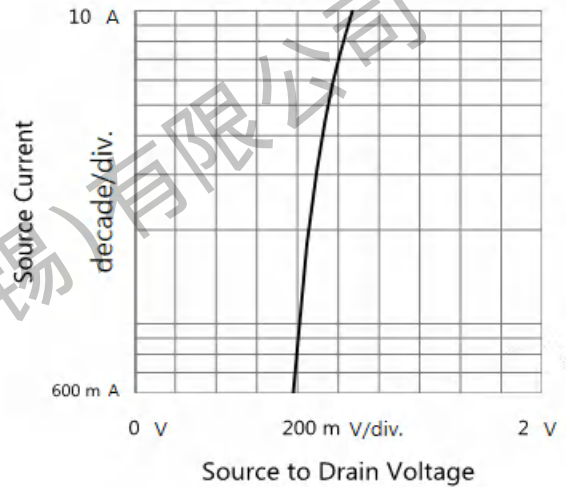


Figure 4: Body Diode Characteristics



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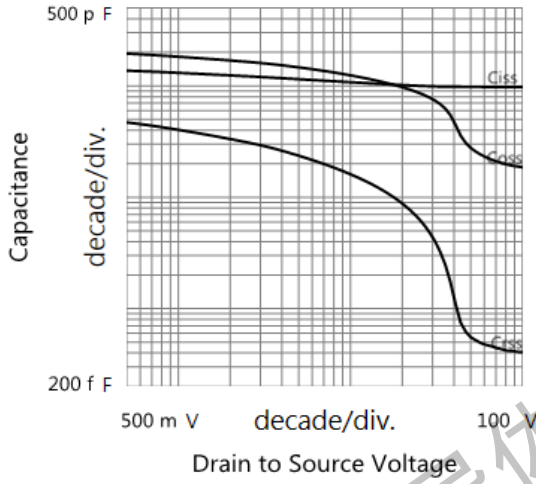


Figure 5: Capacitances

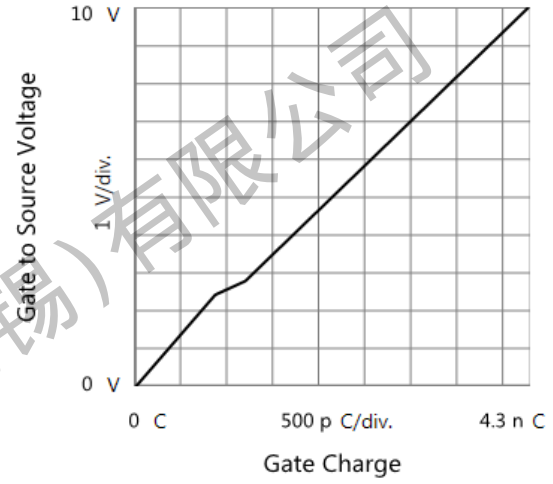


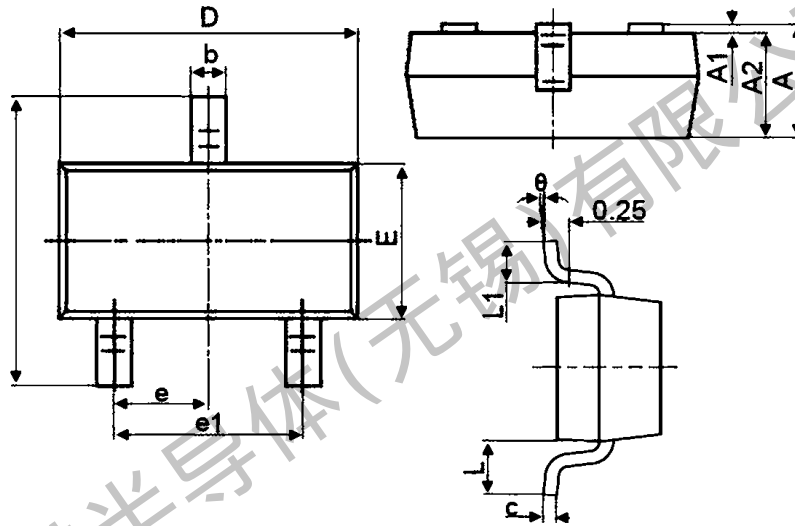
Figure 6: Gate Charge



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Package Mechanical Data:SOT-23



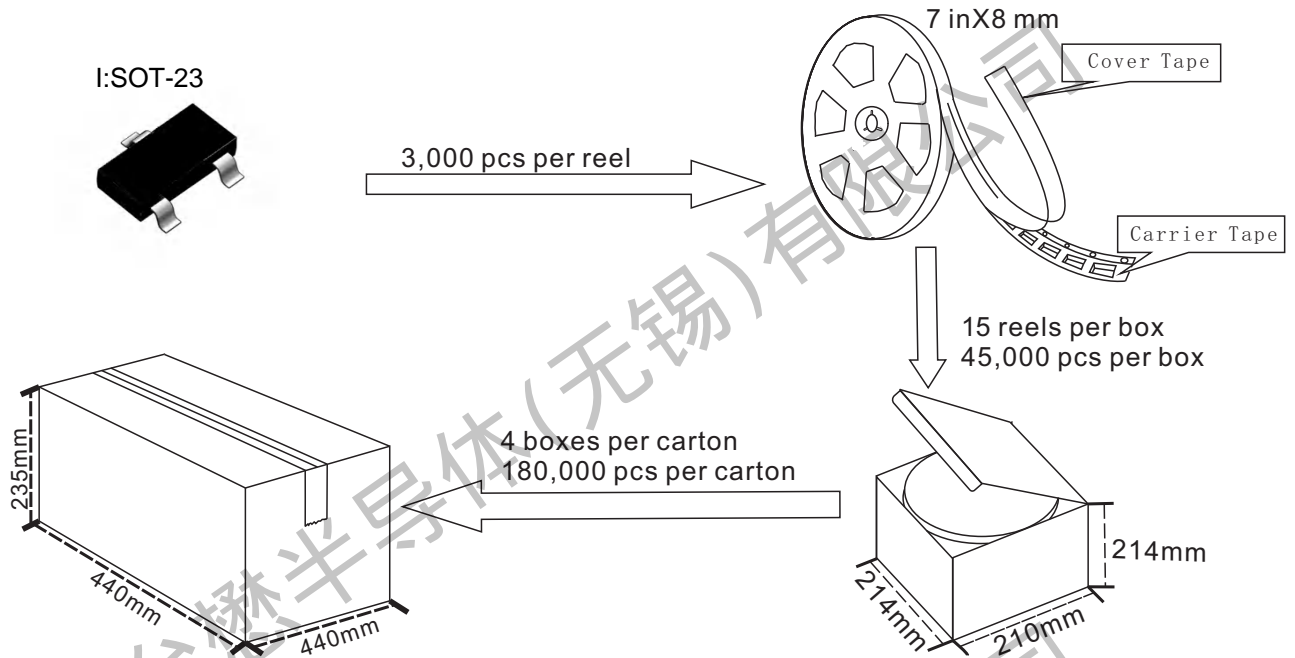
Symbol	Dimensions in Millimeters	
	MIN.	MAX.
A	0.900	1.150
A1	0.000	0.100
A2	0.900	1.050
b	0.300	0.500
c	0.080	0.150
D	2.800	3.000
E	1.200	1.400
E1	2.250	2.550
e	0.950TYP	
e1	1.800	2.000
L	0.550REF	
L1	0.300	0.500
theta	0°	8°

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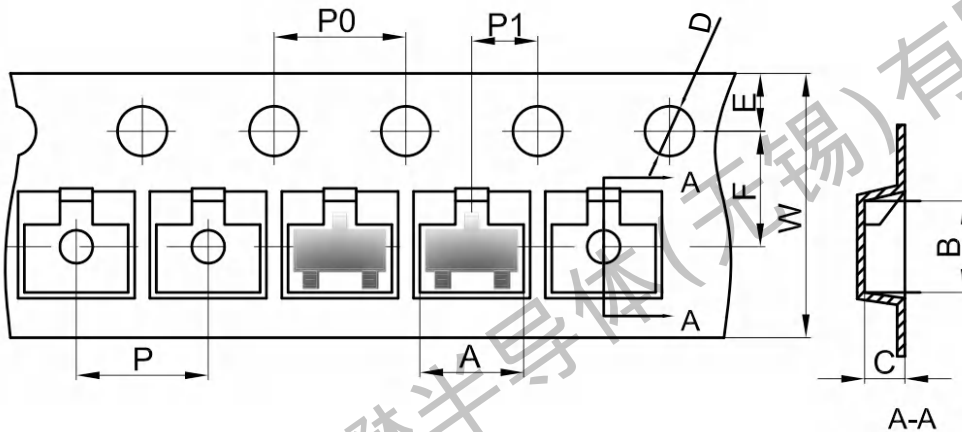
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SOT-23 Packing

1. The method of packaging and dimension are shown as below figure. (Dimension in mm)



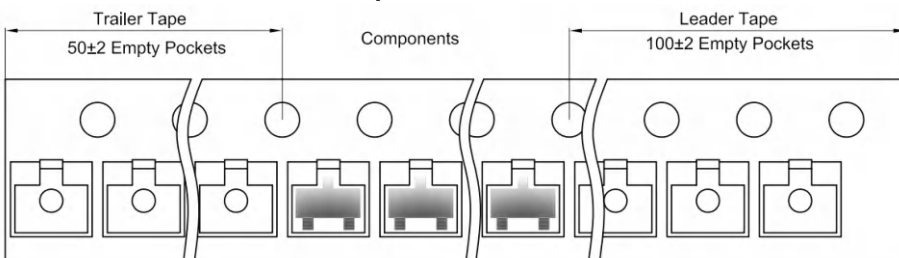
SOT-23 Embossed Carrier Tape



Dimensions are in millimeter

Pkg type	A	B	C	D	E	F	P0	P	P1	W
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00

SOT-23 Tape Leader and Trailer





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Revision history:

Date	Rev	Description	Page
2023.07.01	23.07	Original	